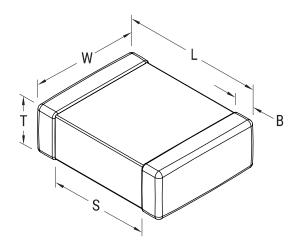




SMD Comm X8G HT150C Flex, Ceramic, 22 pF, 10%, 250 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C Flex
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

nensions		Specific
p Size	1210	Capacita
	3.3mm +/-0.4mm	Measure
	2.6mm +/-0.3mm	Toleranc
	0.78mm +/-0.20mm	Voltage
	1.5mm MIN	Dielectri
	0.6mm +/-0.25mm	Tempera
		Temp. C

Packaging Specifications	
Packaging	T&R, 330mr
Packaging Quantity	10000

Dim Chip L W T S B

0.78mm +/-0.20mm	Voltage DC
1.5mm MIN	Dielectric Withstanding
0.6mm +/-0.25mm	Temperature Range
	Temp. Coefficient
	Capacitance Change w
T&R, 330mm, Plastic Tape	Reference to +25°C and Applied (TCC)
10000	Dissipation Factor

Specifications	
Capacitance	22 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	250 VDC
Dielectric Withstanding Voltage	625 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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